



NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLUX SOLDER SIDE SMD.
3. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
4. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.

REVISION HISTORY			
ECO	REV	DESCRIPTION	APPR
4	PRODUCTION	TIM K.	06/28/16

APPROVALS	LINEAR TECHNOLOGY	
PCB DES.	HZ	
APP ENG.	TITLE: TOP ASSEMBLY DRAWING	
15VIN, +/- 5A MONOLITHIC BUCK REGULATOR		

1630 MCCARTHY BLVD
MILPITAS, CA 95035
PH: (408) 432-1900
www.linear.com
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FOR CUSTOMER USE ONLY

SIZE	IC NO.	REV.
N/A	LTC3623EUD DEMO CIRCUIT 2131A	4
SCALE = NONE	FILENAME: 2131A-4.PCB	SHT 1 OF 1